



**Operational Amplifiers Series** 

# Automotive High Speed Operational Amplifiers

BA3472Yxxx-C, BA3474YFV-C, BA3472WFV-C, BA3474WFV-C

### General Description

BA3472Y, BA3474Y, BA3472W, and BA3474W integrate two or four independent Op-amps on a single chip. These Op-Amps can operate from +3V to +36V (single power supply) with a high slew rate ( $10V/\mu$ s) and high-gain bandwidth (4MHz) characteristics.

#### Features

- Single or dual power supply operation
- Wide operating supply voltage
- Standard Op-Amp Pin-assignments
- High open-loop voltage gain
- Internal ESD protection circuit
- Common-mode Input Voltage Range includes ground level, allowing direct ground sensing
- Wide output voltage range
- AEC-Q100 Qualified

#### Packages

SOP8 SSOP-B8 MSOP8 SSOP-B14 W(Typ.) x D(Typ.) x H(Max.) 5.00mm x 6.20mm x 1.71mm 3.00mm x 6.40mm x 1.35mm 2.90mm x 4.00mm x 0.90mm 5.00mm x 6.40mm x 1.35mm

## Simplified schematic

#### Key Specifications

<i>,</i>	
Wide Operating Supply Voltage:	
Single supply	+3.0V to +36.0V
Dual supply	±1.5V to ±18.0V
Wide Temperature Range:	-40°C to +125°C
Input Offset Voltage:	
BA3472Y, BA3474Y	10mV (Max.)
BA3472W, BA3474W	7.5mV (Max.)
Low Input Offset Current:	6nA (Typ.)
Low Input Bias Current:	100nA (Typ.)
Wide Output Voltage Range:	
VEE+0.3V	to VCC-1.0V(Typ.)
	(VCC-VEE=30V)
High Slew Rate:	10V/μs(Typ.)

■ Gain Band Width: 4MHz(Typ.)

#### Application

- Engine Control Unit
- Electric Power Steering (EPS)
- Anti-Lock Braking System (ABS)
- All automotive application



Figure 1. Simplified schematic (one channel only)

OProduct structure : Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays.

## Pin Configuration(TOP VIEW)

SOP8, SSOP-B8, MSOP8



Pin No.	Symbol
1	OUT1
2	-IN1
3	+IN1
4	VEE
5	+IN2
6	-IN2
7	OUT2
8	VCC

## SSOP-B14



Pin No.	Symbol				
1	OUT1				
2	-IN1				
3	+IN1				
4	VCC				
5	+IN2				
6	-IN2				
7	OUT2				
8	OUT3				
9	-IN3				
10	+IN3				
11	VEE				
12	+IN4				
13	-IN4				
14	OUT4				

Package										
SOP8 SSOP-B8 MSOP8 SSOP-B14										
BA3472YF-C	BA3472YFV-C BA3472WFV-C	BA3472YFVM-C	BA3474YFV-C BA3474WFV-C							

## Ordering Information

В	А	3	4	7	Х	х	Х	Х	x
								1	
Part I	Numbe	r				Packa	age	-	
BA34	72Y					F	: SOP	8	
BA34	72W					FV	: SSO	P-B8	
BA34	74Y						SSO	P-B14	
BA34	74W					FVM	: MSO	P8	

C xx

C: Automotive (Engine control unit, EPS, ABS, and so on) Packaging and forming specification E2: Embossed tape and reel (SOP8/SSOP-B8/SSOP-B14) TR: Embossed tape and reel (MSOP8)

## ●Line-up

Topr	Pa	ckage	Orderable Part Number
	SOP8	Reel of 2500	BA3472YF-CE2
	SSOP-B8	Reel of 2500	BA3472YFV-CE2
-40°C to +125°C	MSOP8	Reel of 3000	BA3472YFVM-CTR
-40 C t0 + 125 C	SSOP-B8	Reel of 2500	BA3472WFV-CE2
	SSOP-B14	Reel of 2500	BA3474YFV-CE2
	SSOP-B14	Reel of 2500	BA3474WFV-CE2

## ● Absolute Maximum Ratings (Ta=25°C)

OBA3472Y, BA3472W, BA3474Y, BA3474W

Parameter	Syr	nbol	Ratings	Unit
Supply Voltage	VCC-VEE		+36	V
		SOP8	1075 <sup>*1*5</sup>	
		SSOP-B8	835 <sup>*1*3</sup>	mW
Power dissipation	Pd	MSOP8	750 <sup>*3*5</sup>	
		SSOP-B14	1350 <sup>*2*3</sup>	
Differential Input Voltage <sup>*6</sup>	V	ïd	+36	V
Input Common-mode Voltage Range	Vi	cm	(VEE-0.3) to VEE+36	V
Operating Supply Voltage	Va	ppr	+3.0Vto+36.0V (±1.5Vto±18.0V)	V
Operating Temperature	Topr		-40 to +125	°C
Storage Temperature	Tstg		-55 to +150	°C
Maximum Junction Temperature	Tjr	nax	+150	°C

Note Absolute maximum rating item indicates the condition which must not be exceeded.

Application of voltage in excess of absolute maximum rating or use out absolute maximum rated temperature environment may cause deterioration of characteristics.

\*1 To use at temperature above  $Ta=25^{\circ}C$  reduce 8.6mW/°C.

\*2 To use at temperature above Ta=25°C reduce 6.7mW/°C.

\*3 To use at temperature above  $Ta=25^{\circ}C$  reduce 6.0mW/°C.

\*4 To use at temperature above  $Ta=25^{\circ}C$  reduce 10.8mW/°C.

\*5 Mounted on a FR4 glass epoxy 4 layers PCB 70mm×70mm×1.6mm (occupied copper area: 70mm×70mm).

\*6 The voltage difference between inverting input and non-inverting input is the differential input voltage. Then input terminal voltage is set to more than VEE.

OBA3472Y (Unless otherwise specified VCC=+15V, VEE=-15V)

Parameter	Symbol	Temperature		Limits		Unit	Condition		
Falameter	Symbol	range	Min.	Тур.	Max.	Unit		Condition	
Innut Offerst Velterre <sup>*7</sup>	)/ie	full receive	-	-	10		Vicm=0V,		
Input Offset Voltage <sup>*7</sup>	Vio	full range	-	-	10	mV	VCC=5V VEE=0V	Vicm=0V OUT=VCC/2	
Input Offset Current *7	lio	25°C	-	6	75	nA	Vicm=0V,	OUT=0V	
		full range	-	-	100	10.0	vioni–o v,		
Input Bias Current *8	lb	25°C	-	100	150	nA	Vicm=0V,		
	10	full range	-	-	200	10.0	vioni–o v,	001-00	
Supply Current	ICC	25°C	-	4	5	mA	RL=∞		
	100	full range	-	-	5.5	110 (			
		25°C	3.7	4	-		VCC=5V	RL=2kΩ	
		full range	3.5	-	-		VEE=0V		
Maximum Output Voltage(High)	VOH	25°C	13.7	14	-	V	RL=10kΩ		
		full range	13.5	-	-				
		25°C	13.5	-	-		RL=2kΩ		
		25°C	-	0.1	0.3		VCC=5V	RL=2kΩ	
		full range	-	-	0.6		VEE=0V		
Maximum Output Voltage(Low)	VOL	25°C	-	-14.7	-14.3	V	RL=10kΩ		
		full range	-	-	-14.0				
		25°C	-	-	-13.5		RL=2kΩ		
Large Signal Voltage Gain	Av	25°C	80	100	-	dB	$RI \ge 2kO$	OUT=±10V	
Large Oignar Voltage Carr	~~	full range	70	-	-	uв		001-1100	
Input Common-mode	Vicm	25°C	0	-	VCC-2.0	V	VCC=5V	OUT=VCC/2	
Voltage Range	VICITI	full range	0	-	VCC-2.6	v	VEE=0V	001-000/2	
Common-mode Rejection Ratio	CMRR	25°C	60	97	-	dB	OUT=0V		
Power Supply Rejection Ratio	PSRR	25°C	60	97	-	dB	Vicm=0V,	OUT=0V	
<b>o</b> ( ) <b>o</b> (* <sup>9</sup>		25°C	10	30	-		VCC=5V	IN+=1V IN-=0V	
Output Source Current *9	Isource	full range	10	-	-	mA	VEE=0V	OUT=0V Only 1ch is short circu	
Output Sink Current *9	loint	25°C	20	30	-	m ^	VCC=5V	IN+=0V IN-=1V	
Oulput Sink Current	lsink	full range	20	-	-	mA	VEE=0V	OUT=5V, Only 1ch is short circu	
Gain Band Width	GBW	25°C	-	4	-	MHz		-	
Claur Data	0.0	25°C	-	10	-	\//···-	Av=1, IN=	-10V to +10V,	
Slew Rate	SR	full range	5	-	-	V/µs	RL=2kΩ		
Channel Separation	CS	25°C	-	120	-	dB		-	

\*7 Absolute value

\*8 Current direction: Since first input stage is composed with PNP transistor, input bias current flows out of IC.

\*9 Under high temperatures, please consider the power dissipation when selecting the output current.

OBA3472W (Unless otherwise specified VCC=+15V, VEE=-15V)

Parameter	Symbol	Temperature	Limits		Unit		Condition	
Parameter	Symbol	range	Min.	Тур.	Max.	Unit		Condition
*10		<i>с</i> н	-	-	7.5		Vicm=0V,	
Input Offset Voltage <sup>*10</sup>	Vio	full range	-	-	7.5	mV	VCC=5V VEE=0V	Vicm=0V OUT=VCC/2
Input Offset Current *10	lio	25°C	-	6	75	nA	Vicm=0V,	
	110	full range	-	-	100	11/ \	vieni=ov,	001-01
Input Bias Current *11	lb	25°C	-	100	150	nA	Vicm=0V,	
	10	full range	-	-	200	10.0	vioni–ov,	001-01
Supply Current	ICC	25°C	-	4	5	mA	RL=∞	
	100	full range	-	-	5.5			
		25°C	3.7	4	-		VCC=5V	RL=2kΩ
		full range	3.5	-	-		VEE=0V	
Maximum Output Voltage(High)	VOH	25°C	13.7	14	-	V	RL=10kΩ	
		full range	13.5	-	-			
		25°C	13.5	-	-		RL=2kΩ	
		25°C	-	0.1	0.3			RL=2kΩ
		full range	-	-	0.6		VCC=5V VEE=0V	
Maximum Output	VOL	Tuirrange	-	-	0.3	V		lsink=1mA
Voltage(Low)	VOL	25°C	-	-14.7	-14.3	v	RL=10kΩ	
		full range	-	-	-14.0			
		25°C	-	-	-13.5		RL=2kΩ	
Lorgo Signal Valtago Coin	A.,	25°C	80	100	-	dB	RL≧2kΩ, OUT=±10V	
Large Signal Voltage Gain	Av	full range	70	-	-	uБ	RL≦2K12,	001=±100
Input Common-mode	Vicm	25°C	0	-	VCC-2.0	V	VCC=5V	OUT=VCC/2
Voltage Range	VICITI	full range	0	-	VCC-2.6	v	VEE=0V	001=000/2
Common-mode Rejection Ratio	CMRR	25°C	60	97	-	dB	OUT=0V	
Power Supply Rejection Ratio	PSRR	25°C	60	97	-	dB	Vicm=0V,	
Output Source Current *12	loourer	25°C	10	30	-		VCC=5V	IN+=1V IN-=0V
Output Source Current	Isource	full range	10	-	-	mA	VEE=0V	OUT=0V Only 1ch is short circuit
Output Sink Current *12	loint	25°C	20	30	-	m ^	VCC=5V	IN+=0V IN-=1V
	lsink	full range	20	-	-	mA	VEE=0V	OUT=5V Only 1ch is short circuit
Gain Band Width	GBW	25°C	-	4	-	MHz		-
Clow Dote	00	25°C	-	10	-	\//···-	Av=1, IN=	-10V to +10V
Slew Rate	SR	full range	5	-	-	V/µs	RL=2kΩ	
Channel Separation	CS	25°C	-	120	-	dB		-
*10 Absolute value	1	1		1	1		1	

\*10 Absolute value

\*11 Current direction: Since first input stage is composed with PNP transistor, input bias current flows out of IC.

\*12 Under high temperatures, please consider the power dissipation when selecting the output current.

OBA3474Y (Unless otherwise specified VCC=+15V, VEE=-15V)

Parameter	Symbol	Temperature		Limits		Unit		Condition	
T didinotor	Cymbol	range	Min.	Тур.	Max.	Onic			
Input Offset Voltage *13	Vio	full range	-	-	10	mV	Vicm=0V,		
input encot voltage		Tail Tailige	-	-	10		VCC=5V VEE=0V	Vicm=0V OUT=VCC/2	
Input Offset Current *13	lio	25°C	-	6	75	nA	Vicm=0V,	OUT=0V	
		full range	-	-	100		11011-01,		
Input Bias Current *14	lb	25°C	-	100	150	nA	Vicm=0V,	OUT=0V	
···		full range	-	-	200				
		25°C	-	8	10		RL=∞		
Supply Current	ICC	full range	-	-	9	mA	VCC=15V	, RL=∞	
			-	-	11		RL=∞		
		25°C	3.7	4	-		VCC=5V	RL=2kΩ	
Maximum Output		full range	3.5	-	-		VEE=0V		
Voltage(High)	VOH	25°C	13.7	14	-	V	RL=10kΩ		
		full range	13.5	-	-				
		25°C	13.5	-	-		RL=2kΩ	1	
		25°C	-	0.1	0.3	VCC=5V VEE=0V V RL=10kΩ		RL=2kΩ	
Maximum Output		full range	-	-	0.6		VEE=0V		
Voltage(Low)	VOL	25°C	-	-14.7	-14.3				
		full range	-	-	-14.0				
		25°C	-	-	-13.5		RL=2kΩ		
Large Signal Voltage Gain	Av	25°C	80	100	-	dB	RL≧2kΩ, OUT=±10V		
		full range	70	-	-				
Input Common-mode	Vicm	25°C	0	-	VCC-2.0	V	VCC=5V	OUT=VCC/2	
Voltage Range		full range	0	-	VCC-2.6		VEE=0V		
Common-mode Rejection Ratio	CMRR	25°C	60	97	-	dB	OUT=0V		
Power Supply Rejection Ratio	PSRR	25°C	60	97	-	dB	Vicm=0V,	OUT=0V	
Output Source Current *15	Isource	25°C	10	30	-	mA	VCC=5V	IN+=1V IN-=0V	
		full range	10	-	-		VEE=0V	OUT=0V Only 1ch is short circu	
Output Sink Current *15	Isink	25°C	20	30	-	mA	VCC=5V	IN+=0V IN-=1V	
e apar enn ouriont		full range	20	-	-			OUT=5V Only 1ch is short circu	
Gain Band Width	GBW	25°C	-	4	-	MHz		-	
Slew Rate	SR	25°C	-	10	-	\//ue	Av=1, IN=	-10V to +10V	
	JR	full range	5	-	-	V/µs	RL=2kΩ		
Channel Separation	CS	25°C	-	120	-	dB		-	

\*13 Absolute value

\*14 Current direction: Since first input stage is composed with PNP transistor, input bias current flows out of IC.

\*15 Under high temperatures, please consider the power dissipation when selecting the output current.

OBA3474W (Unless otherwise specified VCC=+15V, VEE=-15V)

DBA3474W (Unless otherw		Temperature	,	Limits		11-29		Condition	
Parameter	Symbol	range	Min.	Тур.	Max.	Unit		Condition	
Insuit Offent Vielteren *16	Min	full receive	-	-	7.5		Vicm=0V,		
Input Offset Voltage *16	Vio	full range	-	-	7.5	mV	VCC=5V VEE=0V	Vicm=0V OUT=VCC/2	
Input Offset Current *16	lio	25°C	-	6	75	nA	Vicm=0V,		
		full range	-	-	100	10.0	vioni–ov,		
Input Bias Current *17	lb	25°C	-	100	150	nA	Vicm=0V,		
	10	full range	-	-	200	11/ \	vieni=ov,	001-00	
		25°C	-	8	10		RL=∞		
Supply Current	ICC	full range	-	-	9	mA	VCC=15V	, RL=∞	
		iun range	-	-	11		RL=∞		
		25°C	3.7	4	-		VCC=5V	RL=2kΩ	
		full range	3.5	-	-		VEE=0V		
Maximum Output Voltage(High)	VOH	25°C	13.7	14	-	V			
		full range	13.5	-	-		RL=10kΩ		
		25°C	13.5	-	-		RL=2kΩ		
Maximum Output		25°C	-	0.1	0.3			RL=2kΩ	
	VOL	full range	-	-	0.6		VCC=5V VEE=0V		
		Tuirrange	-	-	0.3	V		I sink=1mA	
Voltage(Low)		25°C	-	-14.7	-14.3	v	RL=10kΩ		
		full range	-	-	-14.0				
		25°C	-	-	-13.5		RL=2kΩ		
Large Signal Voltage Gain	Av	25°C	80	100	-	dB	PI > 2kO	OUT=±10V	
Large Signal Voltage Gain	AV	full range	70	-	-	uD	NL≞ZKΩ,	001-±100	
Input Common-mode	Vicm	25°C	0	-	VCC-2.0	V	VCC=5V	OUT=VCC/2	
Voltage Range	VICITI	full range	0	-	VCC-2.6	v	VEE=0V	001=000/2	
Common-mode Rejection Ratio	CMRR	25°C	60	97	-	dB	OUT=0V		
Power Supply Rejection Ratio	PSRR	25°C	60	97	-	dB	Vicm=0V,	OUT=0V	
Output Source Current *18	Isource	25°C	10	30	-	mA	VCC=5V	IN+=1V IN-=0V	
Calput Source Current	isource	full range	10	-	-	ШA	VEE=0V	OUT=0V Only 1ch is short circuit	
Output Sink Current *18	loist	25°C	20	30	-		VCC=5V	IN+=0V IN-=1V	
Output Sink Current <sup>*18</sup>	Isink	full range	20	-	-	mA	VEE=0V	OUT=5V Only 1ch is short circui	
Gain Band Width	GBW	25°C	-	4	-	MHz		-	
Slow Pote	SR	25°C	-	10	-	\//ue	Av=1, IN=	-10V to +10V	
Slew Rate	38	full range	5	-	-	V/µs	$\frac{1}{\mu s} RL=2k\Omega$		
Channel Separation	CS	25°C	-	120	-	dB		-	

\*16 Absolute value

\*17 Current direction: Since first input stage is composed with PNP transistor, input bias current flows out of IC.

\*18 Under high temperatures, please consider the power dissipation when selecting the output current.

### **Description of Electrical Characteristics**

Described below are descriptions of the relevant electrical terms used in this datasheet. Items and symbols used are also shown. Note that item name and symbol and their meaning may differ from those on another manufacturer's document or general document.

#### 1. Absolute maximum ratings

Absolute maximum rating items indicate the condition which must not be exceeded. Application of voltage in excess of absolute maximum rating or use out of absolute maximum rated temperature environment may cause deterioration of characteristics.

- 1.1 Power supply voltage (VCC-VEE) Indicates the maximum voltage that can be applied between the positive power supply terminal and negative power supply terminal without deterioration or destruction of characteristics of internal circuit.
- 1.2 Differential input voltage (Vid) Indicates the maximum voltage that can be applied between non-inverting and inverting terminals without damaging the IC.
- 1.3 Input common-mode voltage range (Vicm)

Indicates the maximum voltage that can be applied to the non-inverting and inverting terminals without deterioration or destruction of electrical characteristics. Input common-mode voltage range of the maximum ratings does not assure normal operation of IC. For normal operation, use the IC within the input common-mode voltage range characteristics.

1.4 Power dissipation (Pd)

Indicates the power that can be consumed by the IC when mounted on a specific board at the ambient temperature 25°C (normal temperature). As for package product, Pd is determined by the temperature that can be permitted by the IC in the package (maximum junction temperature) and the thermal resistance of the package.

#### 2. Electrical characteristics

2.1 Input offset voltage (Vio)

Indicates the voltage difference between non-inverting terminal and inverting terminals. It can be translated into the input voltage difference required for setting the output voltage at 0 V.

- 2.2 Input offset current (lio) Indicates the difference of input bias current between the non-inverting and inverting terminals.
- 2.3 Input bias current (lb) Indicates the current that flows into or out of the input terminal. It is defined by the average of input bias currents at the non-inverting and inverting terminals.
- 2.4 Circuit current (ICC) Indicates the current that flows within the IC under specified no-load conditions.
- 2.5 High level output voltage/low level output voltage (VOH/VOL) Indicates the voltage range of the output under specified load condition. It is typically divided into high-level output voltage and low-level output voltage. High-level output voltage indicates the upper limit of output voltage while Low-level output voltage indicates the lower limit.
- 2.6 Large signal voltage gain (Av) Indicates the amplifying rate (gain) of output voltage against the voltage difference between non-inverting terminal and inverting terminal. It is normally the amplifying rate (gain) with reference to DC voltage.

Av = (Output voltage fluctuation) / (Input offset fluctuation)

- 2.7 Input common-mode voltage range (Vicm) Indicates the input voltage range where IC normally operates.
- 2.8 Common-mode rejection ratio (CMRR) Indicates the ratio of fluctuation of input offset voltage when the input common mode voltage is changed. It is normally the fluctuation of DC.

CMRR = (Change of Input common-mode voltage)/(Input offset fluctuation)

2.9 Power supply rejection ratio (PSRR) Indicates the ratio of fluctuation of input offset voltage when supply voltage is changed. It is normally the fluctuation of DC.

PSRR= (Change of power supply voltage)/(Input offset fluctuation)

- 2.10 Output source current/ output sink current (IOH / IOL) The maximum current that can be output from the IC under specific output conditions. The output source current indicates the current flowing out from the IC, and the output sink current indicates the current flowing into the IC.
- 2.11 Gain Band Width (GBW) The product of the open-loop voltage gain and the frequency at which the voltage gain decreases 6dB/octave.
- 2.12 Slew rate (SR)

Indicates the ratio of the change in output voltage with time when a step input signal is applied.

2.13 Channel separation (CS)

Indicates the fluctuation in the output voltage of the driven channel with reference to the change of output voltage of the channel which is not driven.











Figure 14. Input Bias Current - Supply Voltage

Figure 15. Input Bias Current - Ambient Temperature







Voltage Gain • Phase - Frequency (VCC/VEE=+15V/-15V, Av=40dB RL=2k $\Omega$ , CL=100pF, Ta=25°C)





 $(VCC/VEE=+15V/-15V, Av=0dB, RL=2k\Omega, CL=100pF, Ta=25^{\circ}C)$ 

















(VCC/VEE=+15V/-15V, Av=40dB  $RL=2k\Omega$ , CL=100pF,  $Ta=25^{\circ}C$ )

Input / Output Voltage - Time (VCC/VEE=+15V/-15V, Av=0dB, RL= $2k\Omega$ , CL=100pF, Ta= $25^{\circ}$ C)



## Application Information

NULL method condition for Test circuit1

					T		VCC, \	/EE, EK,	Vicm Unit : V
Parameter	VF	S1	S2	S3	VCC	VEE	EK	Vicm	Calculation
Input Offset Voltage	VF1	ON	ON	OFF	15	-15	0	0	1
Input Offset Current	VF2	OFF	OFF	OFF	15	-15	0	0	2
Input Bias Current	VF3	OFF	ON	OFF	15	-15	0	0	3
	VF4	ON	OFF	OFF					
Lorge Signal Valtage Cain	VF5		ON		15	-15	+10	0	4
Large Signal Voltage Gain	VF6	ON	ON	ON	15	-15	-10	0	4
Common-mode Rejection Ratio	VF7	ON	ON	OFF	15	-15	0	-15	F
(Input Common-mode Voltage Range)	VF8	ON	ON	OFF	15	-15	0	13	5
Power Supply Dejection Datio	VF9				2	-2	0	0	G
Power Supply Rejection Ratio	VF10	ON	ON	OFF	18	-18	0	0	6

-Calculation-

1. Input Offset Voltage (Vio)

$$Vio = \frac{|VF1|}{1 + RF/RS} [V]$$

2. Input Offset Current (lio)  
$$lio = \frac{|VF2-VF1|}{Rix(1+RF/RS)}$$
 [A]

3. Input Bias Current (Ib)

$$Ib = \frac{|VF4-VF3|}{2 \times Ri \times (1+RF/RS)}$$
 [A]

4. Large Signal Voltage Gain (Av)

$$Av = 20 \times Log \frac{\Delta EK \times (1 + RF/RS)}{|VF5 - VF6|} [dB]$$

5. Common-mode Rejection Ratio (CMRR)  $CMRR = 20 \times Log \frac{\Delta Vicm \times (1+RF/RS)}{\mid VF8-VF7 \mid} [dB]$ 

$$PSRR = 20 \times Log \frac{\Delta Vcc \times (1 + RF/RS)}{|VF10 - VF9|} \quad [dB]$$

## Switch Condition for Test Circuit 2





SW No.	SW 1	SW 2	SW 3	SW 4	SW 5	SW 6	SW 7	SW 8	SW 9	SW 10	SW 11	SW 12	SW 13	SW 14
Supply Current	OFF	OFF	OFF	ON	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF
Maximum Output Voltage High	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	ON	OFF
Maximum Output Voltage Low	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	ON	OFF
Output Source Current	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	ON
Output Sink Current	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	ON
Slew Rate	OFF	OFF	OFF	ON	OFF	OFF	OFF	ON	ON	ON	OFF	OFF	OFF	OFF
Gain Bandwidth Product	OFF	ON	OFF	OFF	ON	ON	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Equivalent Input Noise Voltage	ON	OFF	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF	ON	OFF	OFF	OFF



Figure 49. Test Circuit 2 (each Op-Amp)



Figure 50. Slew rate input output wave



Figure 51. Test circuit 3(Channel Separation)

### Examples of circuit

OVoltage follower



Figure 52. Voltage follower circuit

Voltage gain is 0dB.

Using this circuit, the output voltage (OUT) is configured to be equal to the input voltage (IN). This circuit also stabilizes the output voltage (OUT) due to high input impedance and low output impedance. Computation for output voltage (OUT) is shown below.



OInverting amplifier



Figure 53. Inverting amplifier circuit

ONon-inverting amplifier



Figure 54. Non-inverting amplifier circuit

For inverting amplifier, input voltage (IN) is amplified by a voltage gain and depends on the ratio of R1 and R2. The out-of-phase output voltage is shown in the next expression

OUT=-(R2/R1) · IN

This circuit has input impedance equal to R1.

For non-inverting amplifier, input voltage (IN) is amplified by a voltage gain, which depends on the ratio of R1 and R2. The output voltage (OUT) is in-phase with the input voltage (IN) and is shown in the next expression.

OUT=(1 + R2/R1) · IN

Effectively, this circuit has high input impedance since its input side is the same as that of the operational amplifier.

#### Power Dissipation

Power dissipation (total loss) indicates the power that the IC can consume at Ta=25°C (normal temperature). As the IC consumes power, it heats up, causing its temperature to be higher than the ambient temperature. The allowable temperature that the IC can accept is limited. This depends on the circuit configuration, manufacturing process, and consumable power.

Power dissipation is determined by the allowable temperature within the IC (maximum junction temperature) and the thermal resistance of the package used (heat dissipation capability). Maximum junction temperature is typically equal to the maximum storage temperature. The heat generated through the consumption of power by the IC radiates from the mold resin or lead frame of the package. Thermal resistance, represented by the symbol  $\theta ja^{\circ}C/W$ , indicates this heat dissipation capability. Similarly, the temperature of an IC inside its package can be estimated by thermal resistance.

Figure 55(a) shows the model of the thermal resistance of the package. The equation below shows how to compute for the Thermal resistance ( $\theta$ ja), given the ambient temperature (Ta), junction temperature (Tj), and power dissipation (Pd).

 $\theta_{ja} = (T_{jmax} - T_{a}) / Pd$  °C/W · · · · · (I)

The Derating curve in Figure 55(b) indicates the power that the IC can consume with reference to ambient temperature. Power consumption of the IC begins to attenuate at certain temperatures. This gradient is determined by Thermal resistance ( $\theta$ ja), which depends on the chip size, power consumption, package, ambient temperature, package condition, wind velocity, etc. This may also vary even when the same of package is used. Thermal reduction curve indicates a reference value measured at a specified condition. Figure 56(c) and 56(d) shows an example of the derating curve for BA3472Y, BA3472W, BA3474Y and BA3474W.



When using the unit above Ta=25°C, subtract the value above per degree°C.

Mounted on a FR4 glass epoxy 4 layers PCB 70mm × 70mm × 1.6mm (occupied copper area : 70mm × 70mm).

Figure 56. Derating curve

<Reference> When the part is mounted on FR4 glass epoxy 4 layers PCB 70mm × 70mm × 1.6mm (occupied copper area : 70mm × 70mm). SSOP-B8 package : Pd at 125°C is 165mW so Vcc has to be below 27V. MSOP8 package : Pd at 125°C is 150mW so Vcc has to be below 25V. SSOP-B14 package : Pd at 125°C is 270mW so Vcc has to be below 22V.

### Operational Notes

1) Unused circuits

When there are unused op-amps, it is recommended that they are connected as in Figure 57, setting the non-inverting input terminal to a potential within the in-phase input voltage range (Vicm).

2) Input voltage

Applying VEE +36V to the input terminal is possible without causing deterioration of the electrical characteristics or destruction, regardless of the supply voltage. However, this does not ensure normal circuit operation. Please note that the circuit operates normally only when the input voltage is within the common mode input voltage range of the electric characteristics.

3) Power supply (single / dual)

The op-amp operates when the voltage supplied is between VCC and VEE. Therefore, the single supply op-amp can be used as dual supply op-amp as well.



Figure 57. Example of application circuit for unused op-amp

4) Power dissipation Pd

Using the unit in excess of the rated power dissipation may cause deterioration in electrical characteristics including reduced current capability due to the rise of chip temperature. Therefore, please take into consideration the power dissipation (Pd) under actual operating conditions and apply a sufficient margin in thermal design. Refer to the thermal derating curves for more information.

- 5) Short-circuit between pins and erroneous mounting Be careful when mounting the IC on printed circuit boards. The IC may be damaged if it is mounted in a wrong orientation or if pins are shorted together. Short circuit may be caused by conductive particles caught between the pins.
- 6) Operation in a strong electromagnetic field Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.
- 7) Radiation

This IC is not designed to withstand radiation.

8) IC handling

Applying mechanical stress to the IC by deflecting or bending the board may cause fluctuations of the electrical characteristics due to piezo resistance effects.

9) Board inspection

Connecting a capacitor to a pin with low impedance may stress the IC. Therefore, discharging the capacitor after every process is recommended. In addition, when attaching and detaching the jig during the inspection phase, make sure that the power is turned OFF before inspection and removal. Furthermore, please take measures against ESD in the assembly process as well as during transportation and storage.

10) Output capacitor

If a large capacitor is connected between the output pin and GND pin, current from the charged capacitor will flow into the output pin and may destroy the IC when the VCC or VIN pin is shorted to ground or pulled down to 0V. Use a capacitor smaller than 1uF between output and GND.

11) Oscillation by output capacitor

Please pay attention to the oscillation by output capacitor and in designing an application of negative feedback loop circuit with these ICs.

Status of this document

The Japanese version of this document is formal specification. A customer may use this translation version only for a reference to help reading the formal version.

If there are any differences in translation version of this document formal version takes priority.

## Physical Dimensions Tape and Reel Information

SOP8



## SSOP-B8



## MSOP8



## SSOP-B14



## Marking Diagrams







Product Name		Package Type	Marking		
	F	SOP8	3472Y		
BA3472Y	FV	SSOP-B8	72Y		
	FVM	MSOP8	3472Y		
BA3472W		SSOP-B8	72W		
BA3474Y	FV	SSOP-B14	3474Y		
BA3474W		330P-В14	3474W		

## •Land pattern data

			All d	imensions in mm
PKG	Land pitch e	Land space MIE	Land length ≧ℓ 2	Land width b2
SOP8	1.27	4.60	1.10	0.76
SSOP-B8 SSOP-B14	0.65	4.60	1.20	0.35
MSOP8	0.65	2.62	0.99	0.35



## BA3472Yxxx-C, BA3474YFV-C, BA3472WFV-C, BA3474WFV-C

## Revision History

Date	Revision	Changes			
24.Aug.2012	001	New Release			
20.Dec.2012	002	BA3472Y, BA3474Y series and land pattern data inserted.			

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(Note1) Medical Equipment Classification of the Specific Ap	plications
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JAPAN	USA	EU	CHINA	
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CLASSⅣ	CLASSI	CLASSⅢ	CLASSII	

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